

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

5 Claim 1 (currently amended): An integrated circuit package, ~~having central leads comprising:~~

a substrate having an upper surface, a lower surface and a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is forming-formed with a wiring regions arranged at the two sides one side of the long slot, and the wiring regions is formed forming with a plurality of eonneected
10 connection points, and a the length of the wiring regions are-is smaller than a length of the long slot of the substrate;

a resistant layer⁴², which is coated on and in contact with the lower surface⁵⁴ of the substrate⁴⁰, and is located between the long slot⁵⁶ and the wiring region⁵⁸, wherein the resistant layer separates the long slot from the
15 wiring region, and a length of the resistant layer is substantially equal to the length of the wiring region;

a glue layer ~~being-coated~~ on the upper surface of the substrate and ~~being~~ located at ~~the-a~~ periphery of the long slot;

an integrated circuit having a first surface ~~forming-formed~~ with a plurality of
20 bonding pads and a second surface, the first surface being adhered to the glue layer, ~~then-the~~ bonding pads being exposed from the long slot of the substrate;

a plurality of wires, each of which is arranged within the long slot of the substrate and is-electrically connects eonneected-the bonding pad of the integrated circuit to the ~~eonneected-connection~~ point of the substrate; and

25 a first compound layer ~~being-filled~~ within the long slot of the substrate ~~for protecting to protect~~ the each-wires.

Claim 2 (cancelled).

Claim 3 (currently amended): The integrated circuit package ~~having central-~~
leads according to claim 1, wherein the ~~eonneected-connection~~ points of the lower
30 surface of the substrate ~~is-are~~ formed with a ball grid array (BGA).

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Claim 4 (currently amended): The integrated circuit package ~~having central~~
leads according to claim 1, ~~wherein further comprises comprising a second~~
compound layer, ~~which is covered on~~ covers the upper surface of the substrate.